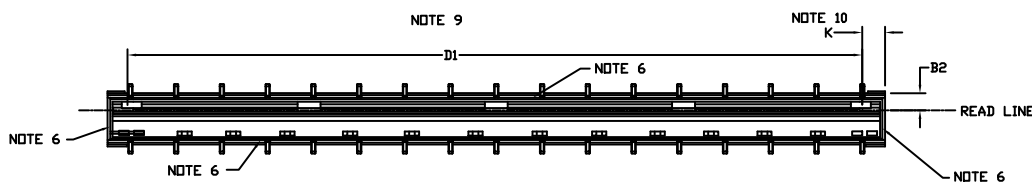
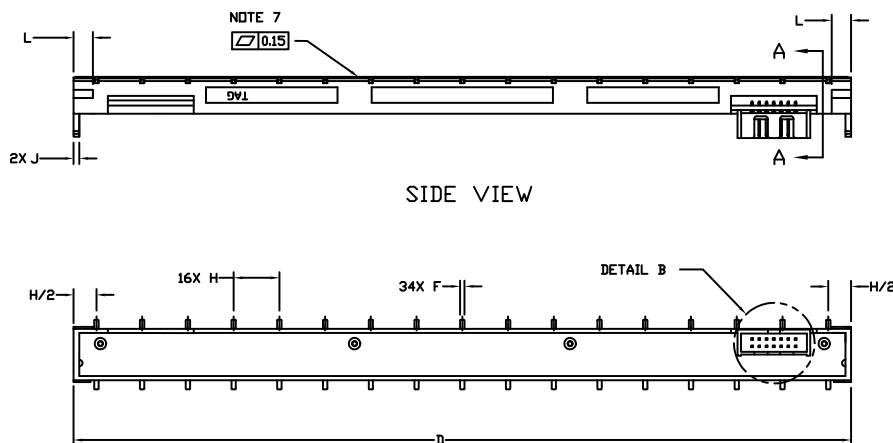
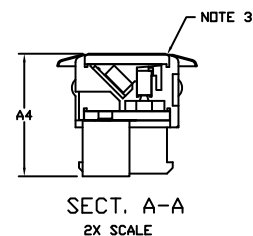


IMAGE SENSOR MODULE
CASE MODAJ
ISSUE O

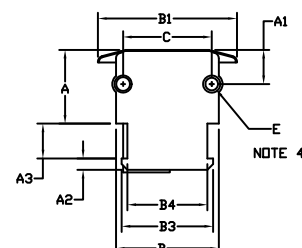
DATE 18 MAY 2010



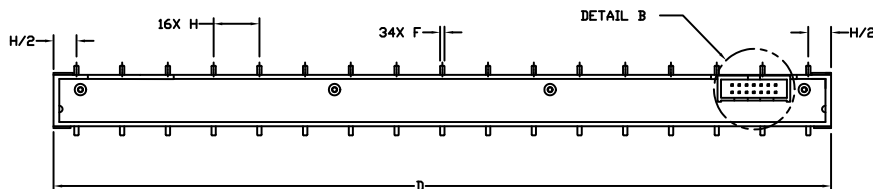
TOP VIEW



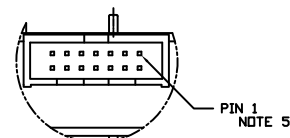
SIDE VIEW



END VIEW
2X SCALE



BOTTOM VIEW



DETAIL B
2X SCALE

DIM	MILLIMETERS	
	MIN	MAX
A	12.60	13.20
A1	5.63	5.93
A2	1.90	2.10
A3	5.98	6.18
A4	21.45	REF
B	17.70	18.30
B1	24.32	REF
B2	5.50	6.50
B3	15.85	16.15
B4	13.85	14.15
C	15.35	15.65
D	271.50	272.50
D1	256.00	REF
E	2.05	2.35
F	1.51	REF
H	16.00	REF
J	2.00	REF
K	7.00	9.00
L	6.80	REF

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEADING EDGE OF THE APPROACH ANGLE ON THE GLASS IS LOWER THAN THE TOP OF THE HOUSING.
4. BORE DEPTH IS 6.0.
5. CONNECTOR, AMP MODEL NUMBER 103308-2, 2X7 PIN, PITCH 2.54.
6. GLASS IS GLUED ON ALL 4 SIDES.
7. GLASS THICKNESS IS 1.85.
8. USE M2.3 SELF TAPPING SCREWS FOR MOUNTING. TORQUE SCREWS BETWEEN 1.80 KGF-CM AND 2.00 KGF-CM.
9. DIMENSION D1 DENOTES THE SCAN LENGTH.
10. DIMENSION K DENOTES THE POSITION OF THE FIRST PIXEL.

DOCUMENT NUMBER: 98AON51324E

Electronic versions are uncontrolled except when accessed directly from the Document Repository.
Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.

DESCRIPTION: IMAGE SENSOR MODULE

PAGE 1 OF 1

onsemi and onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.